



Package Thermal Characteristics

Product	: SC16C554B1B80
Package Type	: 80 I/O, 12x12 mm LQFP
Die Size	: 2.52x2.42x0.38 mm ³
Printed Circuit Board	: JEDEC 4-layer
Pitch	: 0.5 mm
Release Date	: 15 June 2023
Version	: 0
Document No./Agile Ref	: TMASA625
Report Generated By	: Product Innovation

Attributes :

Rating	Board Type ²	Symbol	Value	Unit
Junction to Ambient Thermal Resistance ¹	JESD51-7, 2s2p	R _{θJA}	46.3	°C/W
Junction-to-Top of Package Thermal Characterization Parameter ¹	JESD51-7, 2s2p	Ψ _{JT}	0.8	°C/W
Junction to Case Thermal Resistance ³	JESD51-7, 1s	R _{θJC}	17.6	°C/W

Note :

1. Determined in accordance to JEDEC JESD51-2A natural convection environment. Thermal resistance data in this report is solely for a thermal performance comparison of one package to another in a standardized specified environment. It is not meant to predict the performance of a package in an application-specific environment
2. Thermal test board meets JEDEC specification for this package (JESD51-7).
3. Junction-to-Case thermal resistance determined using an isothermal cold plate. Case temperature refers to the mold surface temperature at the package top side dead centre.
4. Heat dissipation on die: Uniform die power